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## **ABSTRACT OF THE DISCLOSURE**

An embodiment of the invention provides a method for reducing electroplating defects by modifying the concentration of components of a high-acid electroplating solution. For one embodiment the suppressor concentration is increased sufficiently to substantially reduce a plurality of electroplating defects while maintaining adequate gap fill. In such an embodiment the concentration of a chloride in the high-acid electroplating solution is determined as low as possible to reduce defects while still sufficient catalyzing the suppressor to maintain adequate gap fill.